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INTERNATIONAL CENTRE FOR THEORETICAL PHYSICS
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**ICTP - INFN COURSE IN
"BASIC VLSI DESIGN TECHNIQUES"
6 November - 1 December 1989**

ADDITIONAL MATERIAL FOR LECTURES

by

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These are preliminary lectures notes, intended only for distribution to participants.

PROCESS FLOW

nMOS

1. Start with silicon wafer. (p -type)
2. Buffer oxide (ca. $200\text{\AA}$). } 1st layering
3. Si_3N_4 (oxidation mask, $800\text{\AA}$). }
4. Photo resist — FIRST MASK — (Active Area)
5. Boron I-I into exposed areas, p^+ doping.
- 6? Oxidation of p^+ areas to form FIELD OXIDE ($0.5 - 0.9\text{ }\mu\text{m}$ thick) } 2nd layering
 $\xrightarrow{\text{local oxidation process}}$ LOCOS
7. Remove all buffer oxide and Si_3N_4 and thermally grow GATE OXIDE ($250\text{\AA}$) $\rightarrow$ 3rd layering
8. Photo resist — SECOND MASK — (pulldown MOS)
9. Boron to delineated pulldown MOS. (II through gate oxide).
10. Photo resist. — THIRD MASK — (pullup MOS)
11. As or P to delineate pullup MOS.
12. Photo resist — FOURTH MASK — (buried contact)
13. ~~As or P~~ ^{arsenic} to make n^+ region.
14. Reuse of FOURTH MASK to make buried contact available (and oxide free).
15. LAYER IN n^+ -POLY SILICON. ($0.4\text{ }\mu\text{m}$)
(1)

16. Photo-resist - FIFTH MASK - < gates, inter-connections >.

17. The exposed Poly Si and gate oxide is removed. n^+ I-I carried out. The p^+ area under field oxide not doped only exposed active area doped in this self aligned step.

18. Exposed n^+ areas lightly re-oxidized.

19. Layer with insulating oxide

20. Photo resist - SIXTH MASK - < vias >

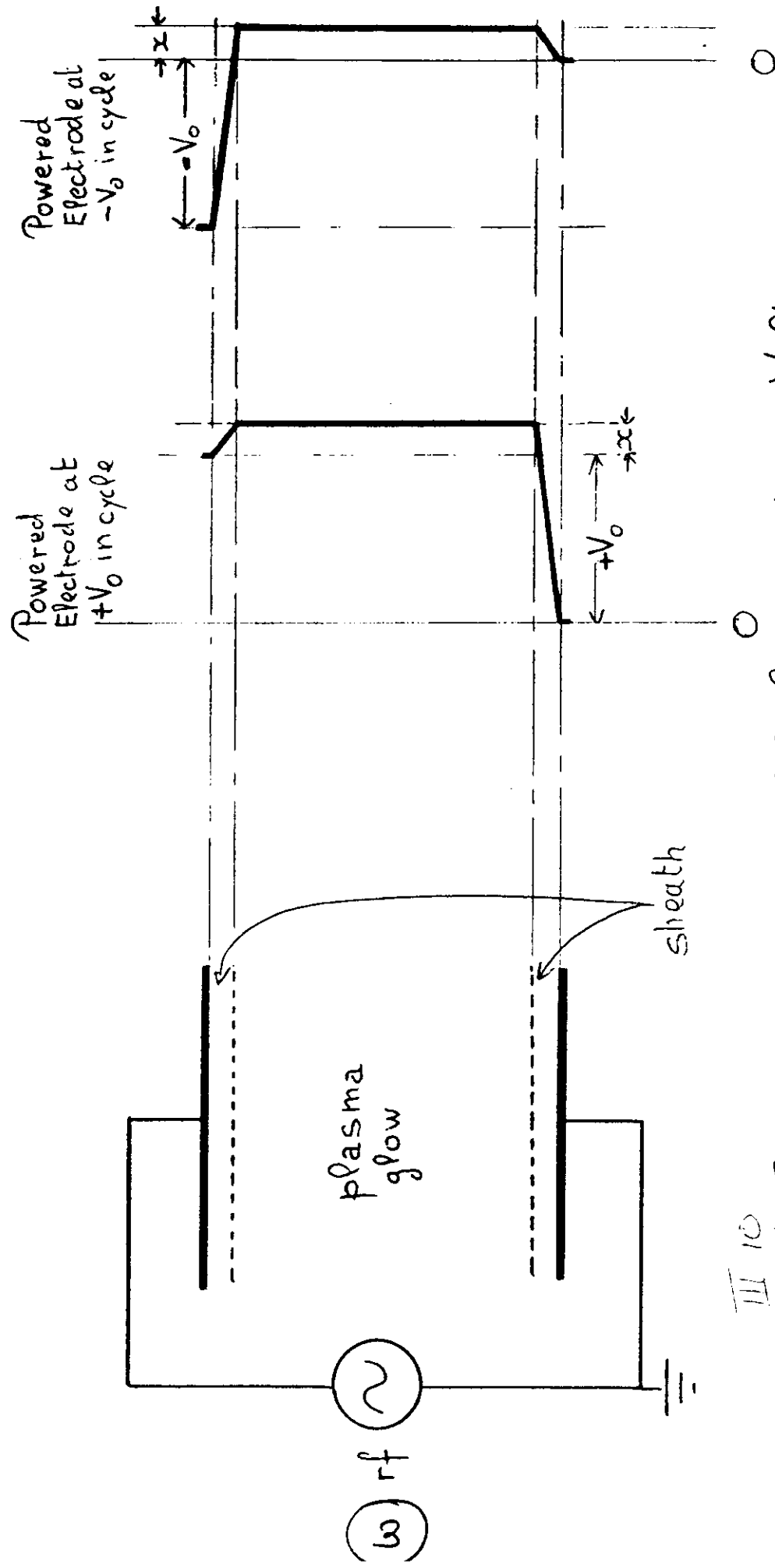
Electrical contacts from buried contact layer and poly-Si to first metal layer.

21. Layer with Aluminium.

22. Photo resist - SEVENTH MASK - < interconnects >

23. Layer with encapsulating over glass.

24. Photo resist. - EIGHTH MASK - < pad areas > expose areas for wire bonding.



III 10
 FIG. V 2. Symmetrical parallel plate reactor. Voltage distribution shown for peaks in the ac. excitation.